

Indium8.9HF

Halogen-Free, No-Clean Solder Paste
for Automotive Applications

AVOID THE VOID[®]



ENHANCED ELECTRICAL RELIABILITY

Indium8.9HF	Enhanced SIR Requirements	Standard SIR (J-STD-004C) Requirements
Minimum SIR requirement	500MOhms	100MOhms
Time	1,000 hours	168 hours
Spacing	0.2mm	0.5mm
Voltage	10V, 50V	5V
SIR coupon	B52/B53	B24

- **Indium8.9HF** shows no dendritic growth under high-power, low-standoff MOSFETs (as validated with automotive customers)
- Proven low ionics <<<1.56 μ grams/sq. cm

Contact our engineers: askus@indium.com

Learn more: www.indium.com

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.



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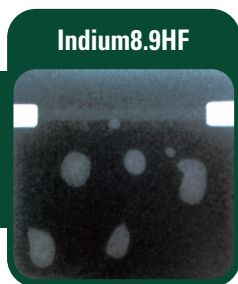
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STABILITY



- Halogen-free
- Low-voiding QFN, DPAK, and BGA packages (<15%)
- 60 hours stencil life (22–28°C and 30–60% RH)
- 12 months refrigerated storage (0–10°C)
- Head-in-pillow/graping elimination with unique flux oxidation barrier technology
- Excellent pin-in-paste and through-hole solderability
- Compatible with different conformal coatings, such as polyurethane, acrylic, and silicone
- Meets HKMC MS184-01 testing criteria



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